

**RoHS
Compliant**

Technical Characteristics

Electrical Characteristics

Contact Resistance : 50mΩ typical, 100mΩ max.
Insulation Resistance : >1000MΩ/500V DC

Solderability

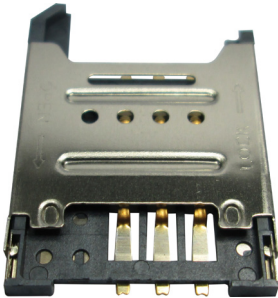
IR Reflow : 260°C, 10 Sec. max.
Manual Soldering : 370°C, 3 Sec. max.

Environmental Characteristics

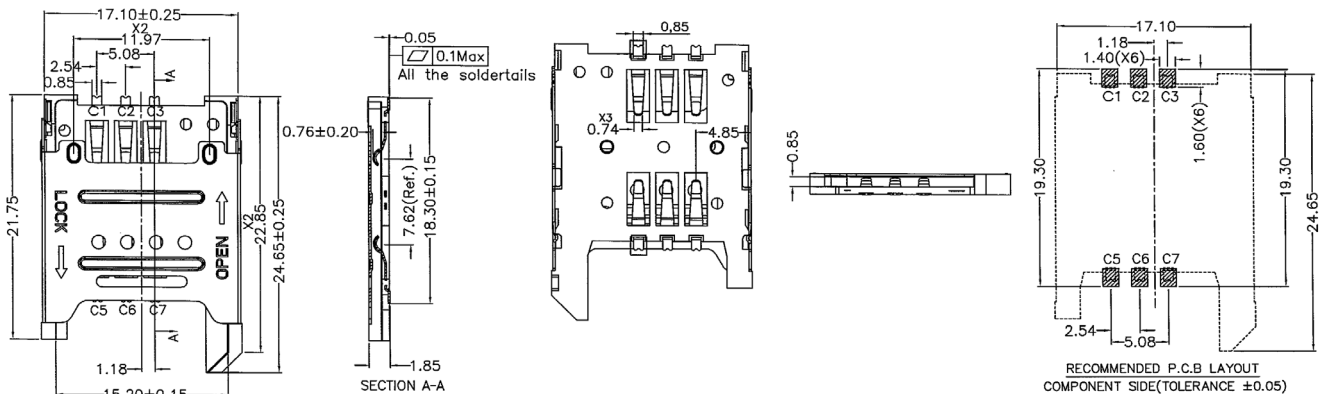
Operating Temperature : -40°C to +85°C
Operating Humidity : 10% to 95% RH

General Characteristics

Dimensions : 24.65mm (L) × 17.1mm (W) × 1.85mm (H)
Weight : Approx. 0.9 g ±0.2g
Durability : 5,000 Cycle min.



Diagram



Dimensions : Millimetres

Part Number Table

Description	Part Number
SIM Card CONN., 6P, SMT	MC002011

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